



Revision: 1.0  
Date: 5-Mar-05

**Statement of Materials, Construction**

**LEAD-FREE -- 6L-DFN -- TABLE OF MATERIAL DECLARATION**

No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.001042	Cu	7440-50-8	0.000996	9.8265	95.5626
				Fe	7439-89-6	0.000024	0.2416	2.3500
				Zn	7440-66-6	0.000001	0.0123	0.1200
				P	7723-14-0	0.000000	0.0031	0.0300
				Spot Plating (Ag)	7440-22-4	0.000021	0.2042	1.9859
2	Die	Silicon Chip	0.000486	Si	7440-21-3	0.000486	4.7900	99.5
3	Die Attach Material	Conductive Epoxy	0.000125	Silver	7440-22-4	0.000094	0.9263	75.00
				Epoxy Resin	Proprietary	0.000019	0.1853	15.00
				Amine	Proprietary	0.000004	0.0408	3.30
				Gamma Butyrolactone	96480	0.000004	0.0408	3.30
				Metal Oxide	Proprietary	0.000004	0.0408	3.30
4	Gold Wire	Gold	0.000045	Au	7440-57-5	0.000045	0.4439	99.99
5	Lead Finish	Tin	0.000122	Sn	7440-31-5	0.000122	1.2082	100
6	Encapsulation	Epoxy Resin	0.008316	Silica Fused	60676-86-0	0.007485	73.8361	90.00
				Epoxy Resin	Proprietary	0.000416	4.1020	5.00
				Phenol Resin	Proprietary	0.000291	2.8714	3.50
				Carbon Black	1333-86-4	0.000042	0.4102	0.50
				Brominated Epoxy Resin	40039-93-8	0.000042	0.4102	0.50
				Antimony trioxide	1309-64-4	0.000042	0.4102	0.50
Total Package weight			0.010137					

**Note:** Composition derived from MSDS and material C of C from Vendors;  
Component Weight based on assembly of generic parts.

**Conclusion:**

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

\* Lead is allowed up to 4% as an alloying agent in copper-based alloys